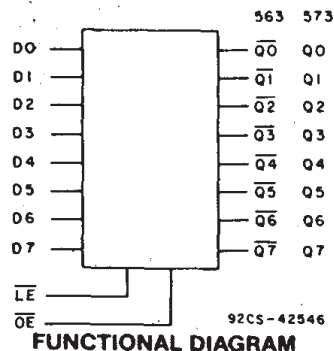


CD54/74AC563, CD54/74AC573 CD54/74ACT563, CD54/74ACT573



Data sheet acquired from Harris Semiconductor
SCHS291



Octal Transparent Latch, 3-State

CD54/74AC/ACT563 - Inverting

CD54/74AC/ACT573 - Non-Inverting

Type Features:

- Buffered inputs
- Typical propagation delay:
4.3 ns @ $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$, $C_L = 50\text{ pF}$

The RCA-CD54/74AC563 and CD54/74AC573 and the CD54/74ACT563 and CD54/74ACT573 octal transparent 3-state latches use the RCA ADVANCED CMOS technology. The outputs are transparent to the inputs when the Latch Enable ($\overline{LE}$) is HIGH. When the Latch Enable ($\overline{LE}$) goes LOW, the data is latched. The Output Enable ($\overline{OE}$) controls the 3-state outputs. When the Output Enable ($\overline{OE}$) is HIGH, the outputs are in the high-impedance state. The latch operation is independent of the state of the Output Enable.

The CD74AC/ACT563 and CD74AC/ACT573 are supplied in 20-lead dual-in-line plastic packages (E suffix) and in 20-lead dual-in-line small-outline plastic packages (M suffix). Both package types are operable over the following temperature ranges: Commercial (0 to 70°C); Industrial (-40 to $+85^\circ\text{C}$); and Extended Industrial/Military (-55 to $+125^\circ\text{C}$).

The CD54AC/ACT563 and CD54AC/ACT573, available in chip form (H suffix), are operable over the -55 to $+125^\circ\text{C}$ temperature range.

Family Features:

- Exceeds 2-kV ESD Protection - MIL-STD-883, Method 3015
- SCR-Latchup-resistant CMOS process and circuit design
- Speed of bipolar FAST*/AS/S with significantly reduced power consumption
- Balanced propagation delays
- AC types feature 1.5-V to 5.5-V operation and balanced noise immunity at 30% of the supply
- $\pm 24\text{-mA}$ output drive current
 - Fanout to 15 FAST* ICs
 - Drives 50-ohm transmission lines

*FAST is a Registered Trademark of Fairchild Semiconductor Corp.

TRUTH TABLE

Output Enable	Latch Enable	Data	AC/ACT563 Output	AC/ACT573 Output
L	H	H	L	H
L	H	L	H	L
L	L	1	H	L
L	L	h	L	H
H	X	X	Z	Z

Note:

L = Low voltage level
H = High voltage level
1 = Low voltage level one set-up time prior to the high to low latch enable transition

h = High voltage level one set-up time prior to the high to low latch enable transition.
X = Don't Care
Z = High Impedance State

This data sheet is applicable to the CD74AC563, CD54/74AC573, and CD54/74ACT573. The CD54AC563 and CD54/74ACT563 were not acquired from Harris Semiconductor.

File Number 1956

CD54/74AC563, CD54/74AC573

CD54/74ACT563, CD54/74ACT573

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE (V_{CC})	-0.5 to 6 V
DC INPUT DIODE CURRENT, I_{IK} (for $V_i < -0.5$ V or $V_i > V_{CC} + 0.5$ V)	± 20 mA
DC OUTPUT DIODE CURRENT, I_{OK} (for $V_o < -0.5$ V or $V_o > V_{CC} + 0.5$ V)	± 50 mA
DC OUTPUT SOURCE OR SINK CURRENT per Output Pin, I_o (for $V_o > -0.5$ V or $V_o < V_{CC} + 0.5$ V)	± 50 mA
DC V_{CC} or GROUND CURRENT (I_{CC} or I_{GND})	± 100 mA*
POWER DISSIPATION PER PACKAGE (P_D):	
For $T_A = -55$ to $+100^\circ\text{C}$ (PACKAGE TYPE E)	500 mW
For $T_A = +100$ to $+125^\circ\text{C}$ (PACKAGE TYPE E)	Derate Linearly at 8 mW/ $^\circ\text{C}$ to 300 mW
For $T_A = -55$ to $+70^\circ\text{C}$ (PACKAGE TYPE M)	400 mW
For $T_A = +70$ to $+125^\circ\text{C}$ (PACKAGE TYPE M)	Derate Linearly at 6 mW/ $^\circ\text{C}$ to 70 mW
OPERATING-TEMPERATURE RANGE (T_A):	
PACKAGE TYPE F	-55 to $+125^\circ\text{C}$
PACKAGE TYPE E, M	-40 to $+125^\circ\text{C}$
STORAGE TEMPERATURE (T_{stg})	-65 to $+150^\circ\text{C}$
LEAD TEMPERATURE (DURING SOLDERING):	
At distance $1/16 \pm 1/32$ in. (1.59 ± 0.79 mm) from case for 10 s maximum	$+265^\circ\text{C}$
Unit inserted into PC board min. thickness $1/16$ in. (1.59 mm) with solder contacting lead tips only	$+300^\circ\text{C}$

*For up to 4 outputs per device; add ± 25 mA for each additional output.

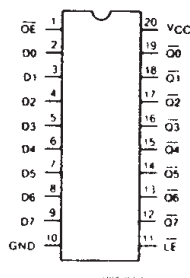
RECOMMENDED OPERATING CONDITIONS:

For maximum reliability, normal operating conditions should be selected so that operation is always within the following ranges:

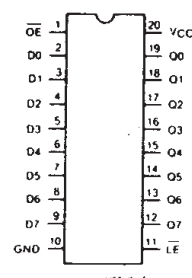
CHARACTERISTIC	LIMITS		UNITS
	MIN.	MAX.	
Supply-Voltage Range, V_{CC} *: (For T_A = Full Package-Temperature Range)			
AC Types	1.5	5.5	V
ACT Types	4.5	5.5	V
DC Input or Output Voltage, V_i, V_o	0	V_{CC}	V
Operating Temperature, T_A :	-55	+125	$^\circ\text{C}$
Input Rise and Fall Slew Rate, dt/dv			
at 1.5 V to 3 V (AC Types)	0	50	ns/V
at 3.6 V to 5.5 V (AC Types)	0	20	ns/V
at 4.5 V to 5.5 V (ACT Types)	0	10	ns/V

*Unless otherwise specified, all voltages are referenced to ground.

9

TERMINAL ASSIGNMENT DIAGRAMS

CD54/74AC563, CD54/74ACT563



CD54/74AC573, CD54/74ACT573

CD54/74AC563, CD54/74AC573

CD54/74ACT563, CD54/74ACT573

STATIC ELECTRICAL CHARACTERISTICS: AC Series

CHARACTERISTICS	TEST CONDITIONS		V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C						UNITS
				+25		-40 to +85		-55 to +125		
	V _I (V)	I _O (mA)		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
High-Level Input Voltage V _{IH}			1.5	1.2	—	1.2	—	1.2	—	V
			3	2.1	—	2.1	—	2.1	—	
			5.5	3.85	—	3.85	—	3.85	—	
Low-Level Input Voltage V _{IL}			1.5	—	0.3	—	0.3	—	0.3	V
			3	—	0.9	—	0.9	—	0.9	
			5.5	—	1.65	—	1.65	—	1.65	
High-Level Output Voltage V _{OH}	V _{IH} or V _{IL}	-0.05	1.5	1.4	—	1.4	—	1.4	—	V
		-0.05	3	2.9	—	2.9	—	2.9	—	
		-0.05	4.5	4.4	—	4.4	—	4.4	—	
		-4	3	2.58	—	2.48	—	2.4	—	
		-24	4.5	3.94	—	3.8	—	3.7	—	
	#, *	-75	5.5	—	—	3.85	—	—	—	
		-50	5.5	—	—	—	—	3.85	—	
Low-Level Output Voltage V _{OL}	V _{IH} or V _{IL}	0.05	1.5	—	0.1	—	0.1	—	0.1	V
		0.05	3	—	0.1	—	0.1	—	0.1	
		0.05	4.5	—	0.1	—	0.1	—	0.1	
		12	3	—	0.36	—	0.44	—	0.5	
		24	4.5	—	0.36	—	0.44	—	0.5	
	#, *	75	5.5	—	—	—	1.65	—	—	
		50	5.5	—	—	—	—	—	1.65	
Input Leakage Current I _I	V _{CC} or GND		5.5	—	±0.1	—	±1	—	±1	μA
3-State Leakage Current I _{OZ}	V _{IH} or V _{IL} V _O = V _{CC} or GND		5.5	—	±0.5	—	±5	—	±10	μA
Quiescent Supply Current, MSI I _{CC}	V _{CC} or GND	0	5.5	—	8	—	80	—	160	μA

#Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

*Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

Technical Data

CD54/74AC563, CD54/74AC573 CD54/74ACT563, CD54/74ACT573

STATIC ELECTRICAL CHARACTERISTICS: ACT Series

CHARACTERISTICS	TEST CONDITIONS		V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C						UNITS
				+25		-40 to +85		-55 to +125		
	V _I (V)	I _O (mA)		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
High-Level Input Voltage V _{IH}			4.5 to 5.5	2	—	2	—	2	—	V
Low-Level Input Voltage V _{IL}			4.5 to 5.5	—	0.8	—	0.8	—	0.8	V
High-Level Output Voltage V _{OH}	V _{IH} or V _{IL} #, * {	-0.05	4.5	4.4	—	4.4	—	4.4	—	V
		-24	4.5	3.94	—	3.8	—	3.7	—	
		-75	5.5	—	—	3.85	—	—	—	
		-50	5.5	—	—	—	—	3.85	—	
Low-Level Output Voltage V _{OL}	V _{IH} or V _{IL} #, * {	0.05	4.5	—	0.1	—	0.1	—	0.1	V
		24	4.5	—	0.36	—	0.44	—	0.5	
		75	5.5	—	—	—	1.65	—	—	
		50	5.5	—	—	—	—	—	1.65	
Input Leakage Current I _I	V _{CC} or GND		5.5	—	±0.1	—	±1	—	±1	μA
3-State Leakage Current I _{OZ}	V _{IH} or V _{IL} V _O = V _{CC} or GND		5.5	—	±0.5	—	±5	—	±10	μA
Quiescent Supply Current, MSI I _{CC}	V _{CC} or GND	0	5.5	—	8	—	80	—	160	μA
Additional Quiescent Supply Current per Input Pin TTL Inputs High 1 Unit Load ΔI _{CC}	V _{CC} -2.1		4.5 to 5.5	—	2.4	—	2.8	—	3	mA

#Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

*Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

ACT INPUT LOADING TABLE

INPUT	UNIT LOAD*	
	ACT563	ACT573
$\overline{OE}$	0.87	0.87
$\overline{Dn}$	0.5	0.5
$\overline{LE}$	0.8	0.8

*Unit load is ΔI_{CC} limit specified in Static Characteristics Chart, e.g., 2.4 mA max. @ 25°C.

CD54/74AC563, CD54/74AC573

CD54/74ACT563, CD54/74ACT573

PREREQUISITE FOR SWITCHING: AC Series

CHARACTERISTICS	SYMBOL	V _{CC} (V)	AMBIENT TEMPERATURE (T _A) -°C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
$\overline{LE}$ Pulse Width	t _w	1.5 3.3* 5†	44 4.9 3.5	— — —	50 5.6 4	— — —	ns
Setup Time Data to $\overline{LE}$	t _{su}	1.5 3.3 5	2 2 2	— — —	2 2 2	— — —	ns
Hold Time Data to $\overline{LE}$	t _H	1.5 3.3 5	33 3.7 2.6	— — —	38 4.2 3	— — —	ns

*3.3 V: min. is @ 3 V

†5 V: min. is @ 4.5 V

SWITCHING CHARACTERISTICS: AC Series; t_r, t_f = 3 ns, C_L = 50 pF

CHARACTERISTICS	SYMBOL	V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Propagation Delays: Data to Qn AC563	t _{PLH} t _{PHL}	1.5 3.3* 5†	— 3.8 2.7	119 13.4 9.5	— 3.7 2.6	131 14.7 10.5	ns
AC573	t _{PLH} t _{PHL}	1.5 3.3 5	— 3.1 2.2	96 10.8 7.7	— 3 2.1	106 11.9 8.5	ns
$\overline{LE}$ on Qn AC563	t _{PLH} t _{PHL}	1.5 3.3 5	— 4.3 3.1	136 15.3 10.9	— 4.2 3	150 16.8 12	ns
AC573	t _{PLH} t _{PHL}	1.5 3.3 5	— 4.3 3.1	136 15.3 10.9	— 4.2 3	150 16.8 12	ns
Output Enable Times	t _{PZL} t _{PZH}	1.5 3.3 5	— 4.1 2.7	119 14.4 9.5	— 4 2.6	131 15.8 10.5	ns
Output Disable Times	t _{PLZ} t _{PHZ}	1.5 3.3 5	— 3.7 3	131 13.1 10.5	— 3.6 2.9	144 14.4 11.5	ns
Power Dissipation Capacitance	C _{PD} §	—	63 Typ.		63 Typ.		pF
Min. (Valley) V _{OH} During Switching of Other Outputs (Output Under Test Not Switching)	V _{OHV} See Fig. 1	5	4 Typ. @ 25°C				V
Max. (Peak) V _{OL} During Switching of Other Outputs (Output Under Test Not Switching)	V _{OLP} See Fig. 1	5	1 Typ. @ 25°C				V
Input Capacitance	C _I	—	—	10	—	10	pF
3-State Output Capacitance	C _O	—	—	15	—	15	pF

*3.3 V: min. is @ 3.6 V
max. is @ 3 V†5 V: min. is @ 5.5 V
max. is @ 4.5 V§C_{PD} is used to determine the dynamic power consumption, per latch.P_D = V_{CC}² f_i (C_{PD} + C_L) where f_i = input frequencyC_L = output load capacitanceV_{CC} = supply voltage.

CD54/74AC563, CD54/74AC573

CD54/74ACT563, CD54/74ACT573

PREREQUISITE FOR SWITCHING: ACT Series

CHARACTERISTICS	SYMBOL	V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
LE Pulse Width	t _w	5†	3.5	—	4	—	ns
Setup Time Data to LE	t _{su}	5	2	—	2	—	ns
Hold Time Data to LE	t _h	5	2.6	—	3	—	ns

†5 V: min. is @ 4.5 V

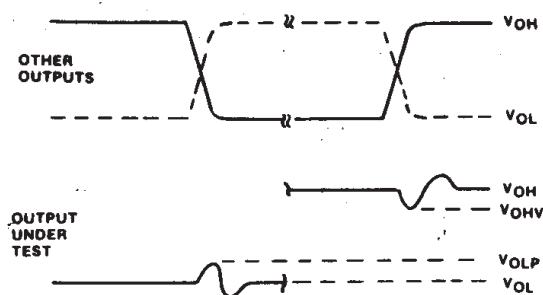
SWITCHING CHARACTERISTICS: ACT Series; t_r, t_f = 3 ns, C_L = 50 pF

CHARACTERISTICS	SYMBOL	V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Propagation Delays: Data to Qn 563	t _{PLH} t _{PHL}	5†					ns
573			2.9	10.4	2.9	11.4	
LE to Qn 563 573	t _{PLH} t _{PHL}	5	3.2	11.4	3.1	12.5	ns
Output Enable Times	t _{PZL} t _{PZH}	5	3.5	12.3	3.4	13.5	ns
Output Disable Times	t _{PLZ} t _{PHZ}	5	3.2	11.4	3.1	12.5	ns
Power Dissipation Capacitance	C _{PD} §	—	63 Typ.		63 Typ.		pF
Min. (Valley) V _{OH} During Switching of Other Outputs (Output Under Test Not Switching)	V _{OHV} See Fig. 1	5	4 Typ. @ 25°C				V
Max. (Peak) V _{OL} During Switching of Other Outputs (Output Under Test Not Switching)	V _{OLP} See Fig. 1	5	1 Typ. @ 25°C				V
Input Capacitance	C _i	—	—	10	—	10	pF
3-State Output Capacitance	C _O	—	—	15	—	15	pF

†5 V: min. is @ 5.5 V
max. is @ 4.5 V§C_{PD} is used to determine the dynamic power consumption, per latch. $P_D = V_{CC}^2 f_i (C_{PD} + C_L) + V_{CC} \Delta I_{CC}$ where f_i = input frequencyC_L = output load capacitanceV_{CC} = supply voltage.

CD54/74AC563, CD54/74AC573 CD54/74ACT563, CD54/74ACT573

PARAMETER MEASUREMENT INFORMATION

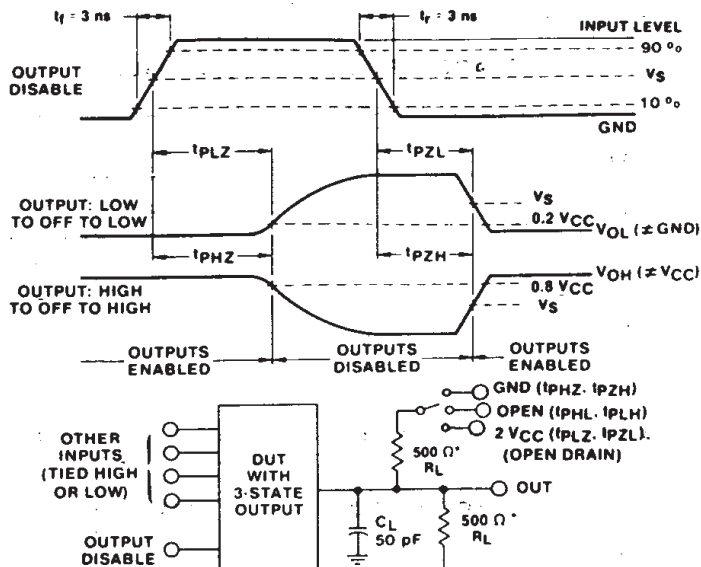


NOTES:

1. V_{OHV} and V_{OLP} are measured with respect to a ground reference near the output under test.
2. INPUT PULSES HAVE THE FOLLOWING CHARACTERISTICS:
PRR: 1 MHz, $t_r = 3$ ns, $t_f = 3$ ns, SKEW 1 ns.
3. R.F. FIXTURE WITH 700-MHz DESIGN RULES REQUIRED.
IC SHOULD BE SOLDERED INTO TEST BOARD AND BYPASSED WITH 0.1 μ F CAPACITOR. SCOPE AND PROBES REQUIRE 700-MHz BANDWIDTH.

92CS-4240E

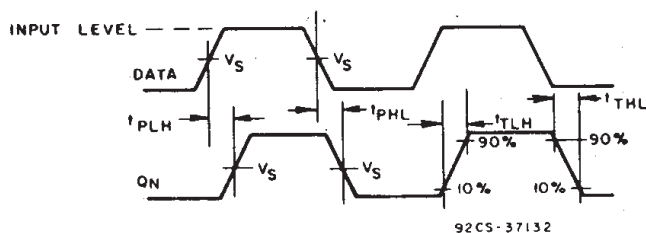
Fig. 1 - Simultaneous switching transient waveforms.



92CM-42405

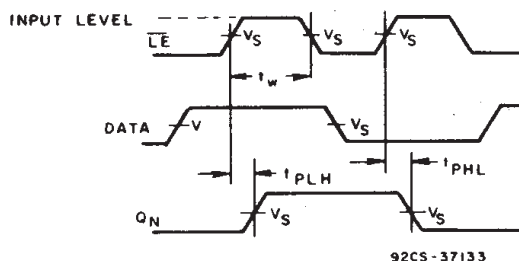
*FOR AC SERIES ONLY: WHEN $V_{CC} = 1.5$ V, $R_L = 1$ k Ω

Fig. 2 - Three-state propagation delay waveforms and test circuit.



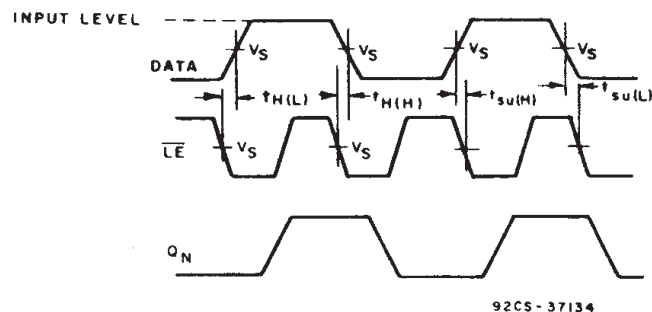
92CS-37132

Fig. 3 - Data to Qn output propagation delays.



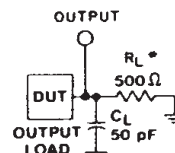
92CS-37133

Fig. 4 - Latch enable propagation delays.



92CS-37134

Fig. 5 - Latch enable prerequisite times.



*FOR AC SERIES ONLY: WHEN
 $V_{CC} = 1.5$ V, $R_L = 1$ k Ω

92CS-42189

Fig. 6 - Test circuit.

	CD54/74AC	CD54/74ACT
Input Level	V_{CC}	3 V
Input Switching Voltage, V_S	0.5 V_{CC}	1.5 V
Output Switching Voltage, V_S	0.5 V_{CC}	0.5 V_{CC}

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
CD54AC573F3A	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD54AC573F3A
CD54AC573F3A.A	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD54AC573F3A
CD54ACT573F3A	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD54ACT573F3A
CD54ACT573F3A.A	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD54ACT573F3A
CD74AC573E	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74AC573E
CD74AC573E.A	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74AC573E
CD74AC573M	Obsolete	Production	SOIC (DW) 20	-	-	Call TI	Call TI	-55 to 125	AC573M
CD74AC573M96	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC573M
CD74AC573M96.A	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC573M
CD74ACT573E	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74ACT573E
CD74ACT573E.A	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74ACT573E
CD74ACT573M	Obsolete	Production	SOIC (DW) 20	-	-	Call TI	Call TI	-55 to 125	ACT573M
CD74ACT573M96	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT573M
CD74ACT573M96.A	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT573M

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF CD54AC573, CD54ACT573, CD74AC573, CD74ACT573 :

- Catalog : [CD74AC573](#), [CD74ACT573](#)
- Military : [CD54AC573](#), [CD54ACT573](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74AC573M96	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
CD74ACT573M96	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74AC573M96	SOIC	DW	20	2000	356.0	356.0	45.0
CD74ACT573M96	SOIC	DW	20	2000	356.0	356.0	45.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
CD74AC573E	N	PDIP	20	20	506	13.97	11230	4.32
CD74AC573E.A	N	PDIP	20	20	506	13.97	11230	4.32
CD74ACT573E	N	PDIP	20	20	506	13.97	11230	4.32
CD74ACT573E.A	N	PDIP	20	20	506	13.97	11230	4.32

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

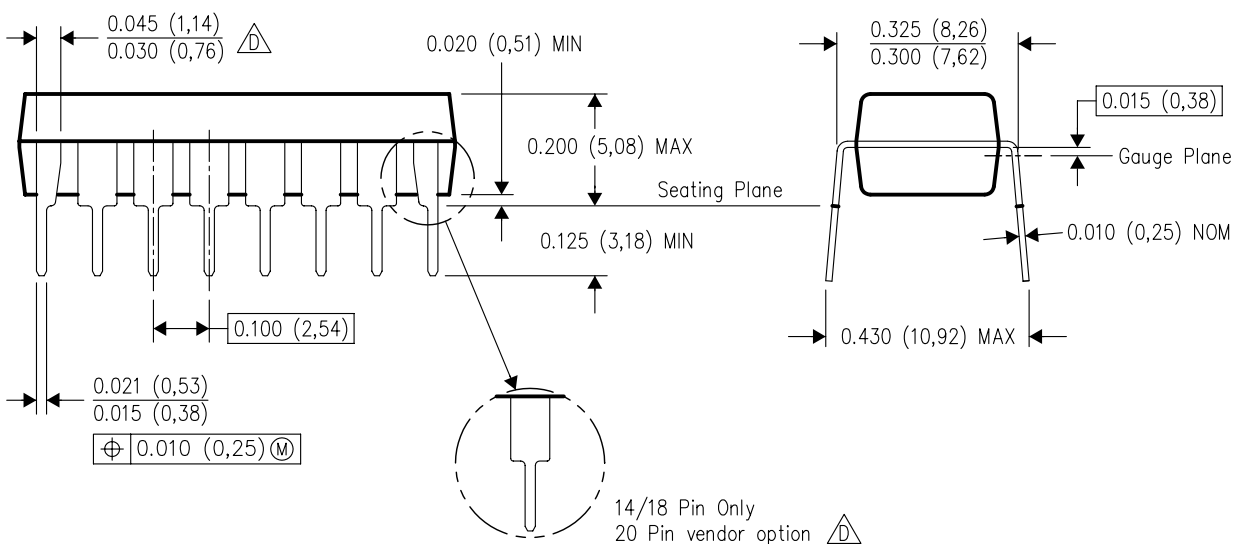
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE

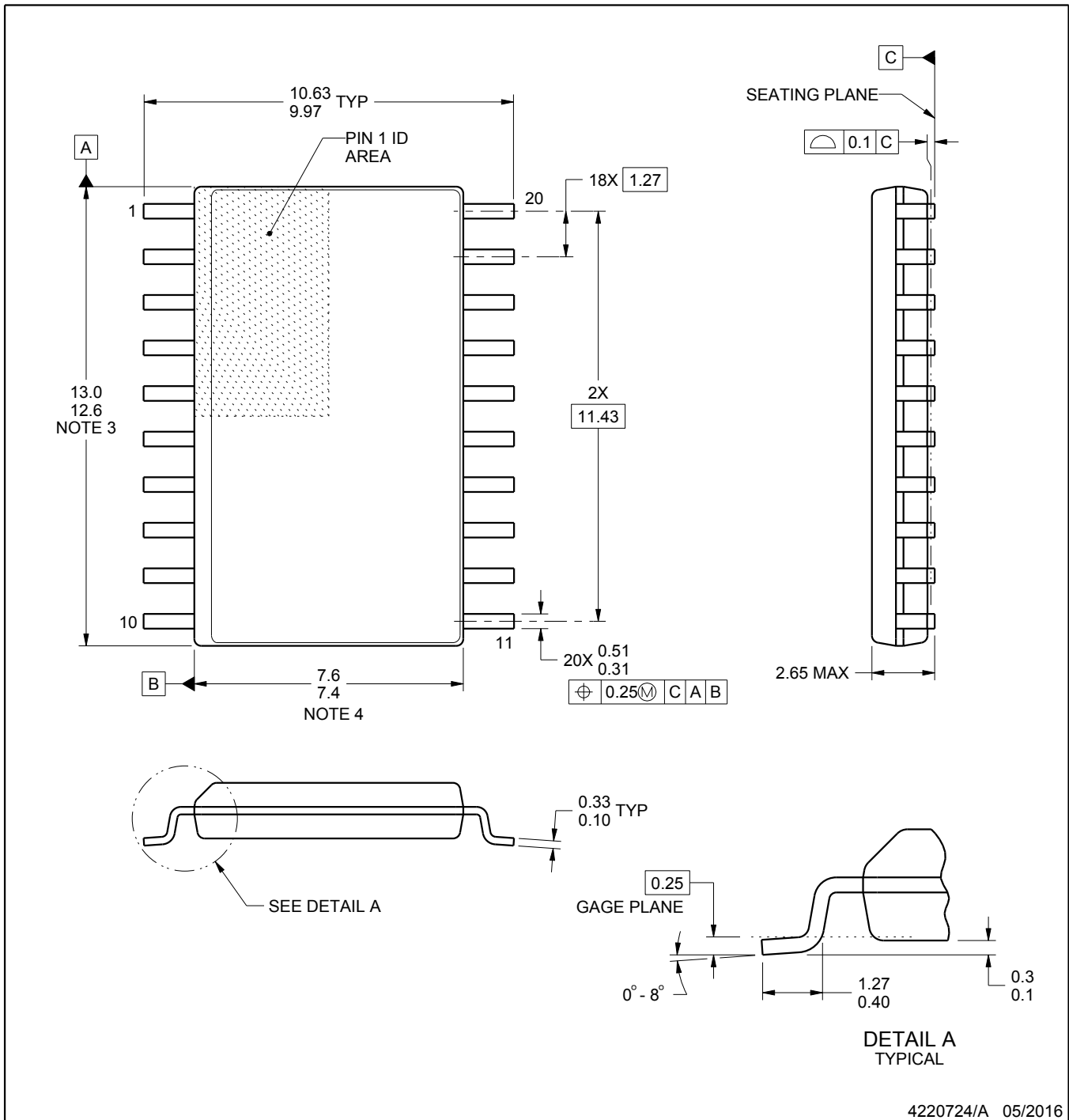


PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 -  The 20 pin end lead shoulder width is a vendor option, either half or full width.



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NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

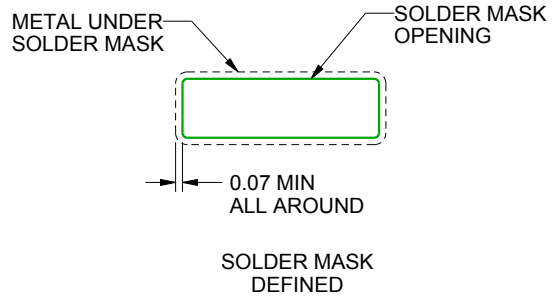
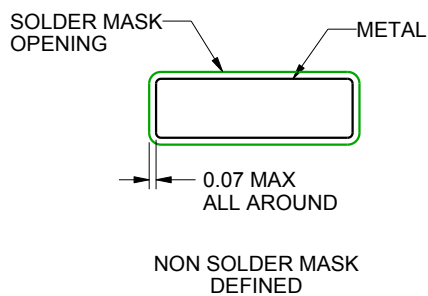
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

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NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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